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13. ABSTRACT (Maximum 200 words) <p>The near-surface regions of polycrystalline <math>Si_3N_4</math> were modified by ion implantation and post-implantation annealing. Metallographically polished bars and disks 3 mm in diameter and ranging in thickness from 250 to 500 <math>\mu m</math> were implanted of co-implanted with <math>Al^+</math>, <math>B^+</math> and <math>N^+</math> to fluences up to <math>2 \times 10^{16}</math> ions/<math>cm^2</math>, using implantation energies up to 300 keV. Some of the implanted material was post-implantation annealed at temperatures in the neighborhood of 1100 <math>^{\circ}C</math>. The indentation fracture toughness was found to increase by more than 15 % for certain combinations of fluence, implantation species and post-implantation annealing temperature.</p> <p style="text-align: center;">DTIC QUALITY INSPECTED 4</p>				
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Final Report

Ion implantation experiments were performed on  $\text{Si}_3\text{N}_4$  produced by Cercon Inc., Vista, CA, for the purpose of improving its fracture toughness. The material contained 6 wt. %  $\text{Y}_2\text{O}_3$  and 3 wt. %  $\text{Al}_2\text{O}_3$  as sintering aids, and was HIPped. Pieces measuring  $3 \times 5 \times 5$  mm were cut from the bars provided and metallographically polished in preparation for the first ion implantations. In these experiments specimens of  $\text{Si}_3\text{N}_4$  were implanted individually with  $\text{B}^+$  and  $\text{Al}^+$  or co-implanted with  $\text{B}^+ + \text{N}^+$  and  $\text{Al}^+ + \text{N}^+$ . These choices were dictated primarily by the fact that B and Al are strong nitride formers. The ion implantations were performed at the Hughes Malibu Research Laboratories, using an implanter under the supervision of Dr. R. G. Wilson. The implantation conditions used are summarized in Table 1. The doses were small, but were conveniently attained within a few hours of implantation using the ion beam fluxes available. Post-implantation annealing was done for 24 h at 1000, 1100 and 1200 °C in a  $\text{N}_2$  atmosphere, the purpose of which was to limit the extent of oxidation rather than nitriding the implanted specimens.

The apparent fracture toughness,  $K_{\text{IC}}$ , was measured using the indentation-toughness method [1]. This method predicts that  $K_{\text{IC}}$  is determined by the equation

$$K_{\text{IC}} = \frac{\chi P}{c^{3/2}}, \quad (1)$$

where  $2c$  is the length of the radial/median cracks that originate at the corners of the indentation under load  $P$ . The constant  $\chi$  is obtained from the equation

$$\chi = \delta \left( \frac{E}{H} \right)^{1/2}, \quad (2)$$

where  $E$  is Young's modulus,  $H$  is the Vickers hardness and  $\delta$  is another constant obtained from the equation [2]

$$\delta = \frac{\psi}{24(1-2\nu)(\sqrt{2}\pi \tan \phi)^{2/3}}, \quad (3)$$

where  $\nu$  is Poisson's ratio (0.27 for  $\text{Si}_3\text{N}_4$ ),  $2\phi$  is the apex angle of the Vickers indenter and  $\psi$  is another constant determined from the geometry of the crack. When the specimen is large compared to  $c$ ,  $\psi$  takes on the value 1.2 [3-5], which we have used throughout.

Measurements were initially made using an indentation load of 3.5 kg, but at this value of  $P$  the indentation cracks that formed in the annealed specimens were difficult to observe, partly due to limited oxidation of the surface, hence subsequent specimens were indented using  $P = 7.35$  kg (34.3 N). Within the limits of experimental error there were no significant variations of hardness with any combination of implantation and post-implantation annealing. This is undoubtedly not because implantation has no effect on hardness, but because the large loads used cause indentations that far exceed the ion ranges (Table 1).

The results of these experiments are summarized in Figs. 1 to 3. In general, implantation with  $\text{Al}^+$  ions was more effective than implantation with  $\text{B}^+$  ions in increasing  $K_{\text{IC}}$  of the  $\text{Si}_3\text{N}_4$ , though the increase in  $K_{\text{IC}}$  exceeded 15 % in only two cases ( $\text{Al}^+$ -as-implanted to a dose of  $10^{16}$  and  $\text{Al}^+$  annealed at 1100 °C after implanting to  $2.5 \times 10^{16}$  ions/cm<sup>2</sup>). Co-implantation with  $\text{N}^+$  was done to higher total doses, and noticeably reduces the values of  $K_{\text{IC}}$  in the as-implanted condition. However, annealing the  $\text{Al}^+$ -implanted  $\text{Si}_3\text{N}_4$  at 1000 °C increased  $K_{\text{IC}}$  by about 18 % over that of unimplanted material, while the toughness of the  $\text{B}^+$ -implanted  $\text{Si}_3\text{N}_4$  increased by about the same amount on annealing at 1100 °C.

A second series of implantation experiments was performed on metallographically polished bars and disks of  $\text{Si}_3\text{N}_4$ . The disks were 3 mm in diameter and ranged in thickness from 250 to 500  $\mu\text{m}$ . The intent of these experiments was to perform controlled-flaw tests [6,7], which require indentation at specific loads prior to

testing, in preparation for testing in our miniaturized disk-bend testing apparatus [8]. The thinner disks were to be indented at lower loads, while the thicker ones were to be indented using larger loads (up to ~10 kg on our microhardness indentation machine). A summary of the irradiation conditions is presented in Table 2. Unfortunately, the grant period expired, the funds were exhausted, and it was not possible to complete the planned experiments on the mechanical behavior of the implanted disks.

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Table 1. Ion implantation conditions for the initial experiments.

Ion Species	Ion Energy (keV)	Fluence (ions/cm <sup>2</sup> )	Range (nm)
Al	300	10 <sup>15</sup>	315
"	"	10 <sup>16</sup>	"
"	"	2.5 × 10 <sup>16</sup>	"
Al	300	2.5 × 10 <sup>16</sup>	315
+ N	240	2.5 × 10 <sup>16</sup>	"
B	300	10 <sup>15</sup>	540
"	"	10 <sup>16</sup>	"
B	200	10 <sup>16</sup>	385
+ N	300	10 <sup>16</sup>	"

Table 2. Ion implantation conditions for the Si<sub>3</sub>N<sub>4</sub> disks and bars.

Specimen Type	Ion Species	Ion Energy (keV)	Fluence (ions/cm <sup>2</sup> )
3 × 5 mm bar and 32 disks	Al + N	Al: 300 N: 225	2.5 × 10 <sup>16</sup> each
3 × 5 mm bar and 32 disks	B + Al	B: 200 N: 300	1.0 × 10 <sup>16</sup> each
3 × 5 mm bar and 32 disks	Al	300	2.5 × 10 <sup>16</sup>
16 disks	Al	300	10 <sup>16</sup>

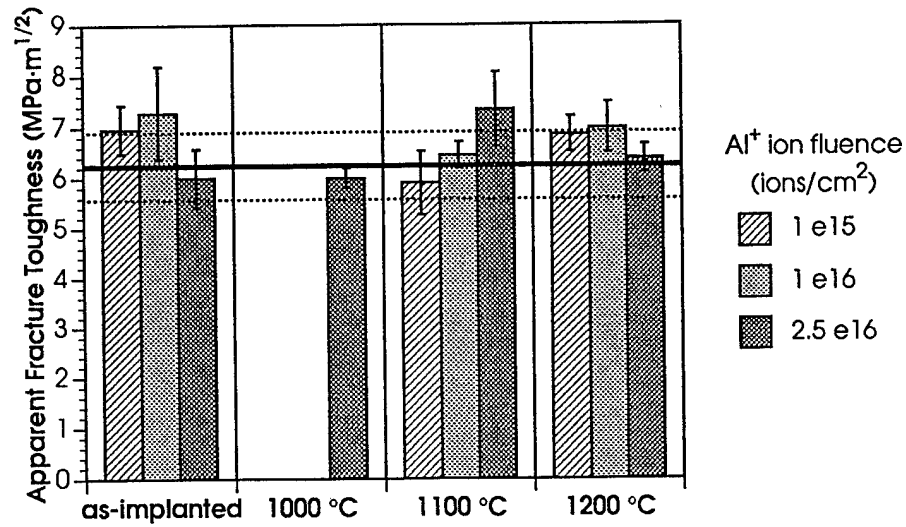


Figure 1. Apparent fracture toughness,  $K_c$ , of  $\text{Si}_3\text{N}_4$  after implantation of  $\text{Al}^+$  ions to the fluences indicated, and post-implantation annealing. The heavy horizontal line represents the average value of  $K_c$  of the as-received material, and the dashed lines the standard deviation. The  $\text{Si}_3\text{N}_4$  implanted with  $\text{Al}^+$  to the lower two doses was not annealed at 1000 °C.

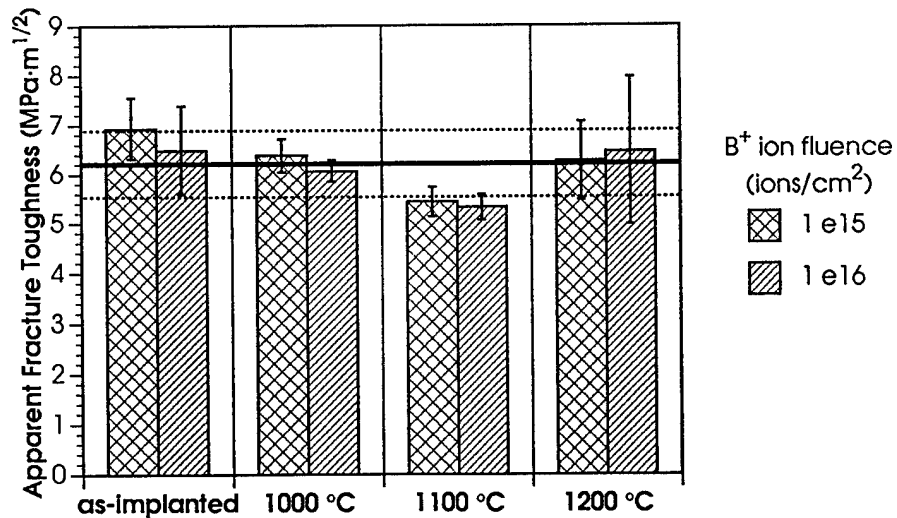


Figure 2. Apparent fracture toughness,  $K_c$ , of  $\text{Si}_3\text{N}_4$  after implantation of  $\text{B}^+$  ions to the fluences indicated, and post-implantation annealing.

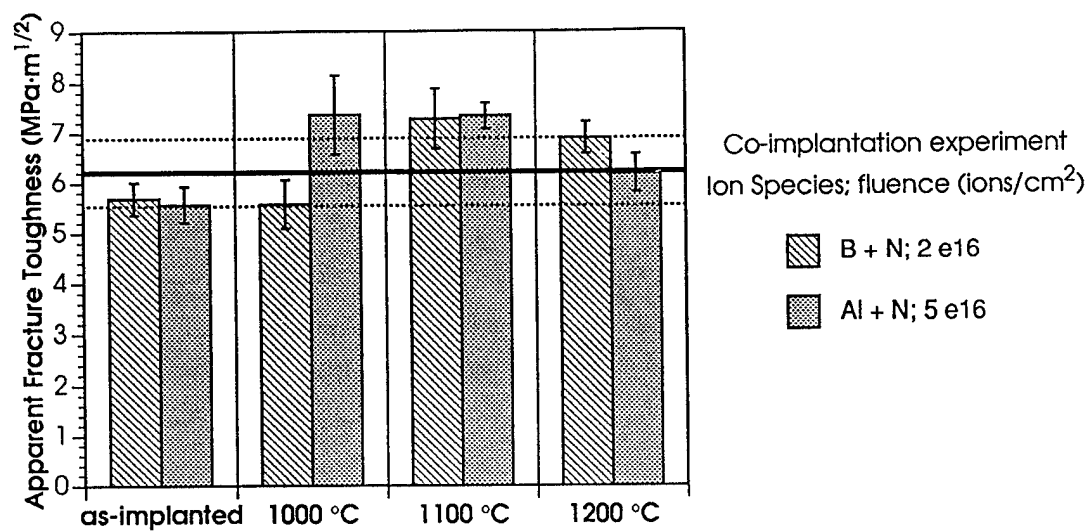


Figure 3. Apparent fracture toughness,  $K_{IC}$ , of  $\text{Si}_3\text{N}_4$  after co-implantation of  $\text{Al}^+ + \text{N}^+$  and  $\text{B}^+ + \text{N}^+$  ions to the fluences indicated, and post-implantation annealing.